

# AMENDMENT TRANSMITTAL LETTER

Docket No.  
M4065.0159/P159-A

Application No.  
09/902,691

Filing Date  
July 12, 2001

Examiner  
P. Brock

Art Unit  
2815

Applicant(s): Li Li, et al.

Invention: METHOD OF CONTROLLING SRIATIONS AND CD LOSS IN CONTACT OXIDE ETCH

## TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	28	- 26 =	1	x 18.00	36.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					36.00

Large Entity

Small Entity

No additional fee is required for this amendment.

Please charge Deposit Account No. \_\_\_\_\_ in the amount of \$ \_\_\_\_\_. A duplicate copy of this sheet is enclosed.

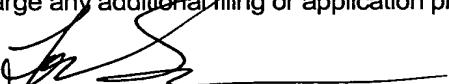
A check in the amount of \$ \_\_\_\_\_ to cover the filing fee is enclosed.

Payment by credit card. Form PTO-2038 is attached.

The Commissioner is hereby authorized to charge and credit Deposit Account No. 04-1073 as described below. A duplicate copy of this sheet is enclosed.

Credit any overpayment.

Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

  
Thomas J. D'Amico  
Attorney Reg. No.: 28,371

Dated: September 26, 2002

DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP  
2101 L Street NW  
Washington, DC 20037-1526  
(202) 828-2232

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**FEE TRANSMITTAL**  
**SEP 26 2002** **for FY 2002**

Patent fees are subject to annual revision.

PATENT &amp; TRADEMARK OFFICE

Applicant claims small entity status. See 37 CFR 1.27

**TOTAL AMOUNT OF PAYMENT**

(\$ 36.00)

**Complete if Known**

Application Number	09/902,691
Filing Date	July 12, 2001
First Named Inventor	Li Li
Examiner Name	P. Brock
Group Art Unit	2815
Attorney Docket No.	M4065.0159/P159-A

**METHOD OF PAYMENT (check all that apply)**

<input type="checkbox"/> Check	<input checked="" type="checkbox"/> Credit Card	<input type="checkbox"/> Money Order	<input type="checkbox"/> Other	<input type="checkbox"/> None
<input type="checkbox"/> Deposit Account				

Deposit Account Number **04-1073**Deposit Account Name **Dickstein Shapiro Morin & Oshinsky LLP**

The Commissioner is hereby authorized to: (check all that apply)

- |   |   |
|---|---|
| <input type="checkbox"/> Charge fee(s) indicated below  | <input checked="" type="checkbox"/> Credit any overpayments |
| <input type="checkbox"/> Charge any additional fee(s) during the pendency of this application |   |
| <input type="checkbox"/> Charge fee(s) indicated below, except for the filing fee             |   |

to the above-identified deposit account.

**FEE CALCULATION (continued)****3. ADDITIONAL FEES****Large Entity      Small Entity**

Fee Code	Fee (\$)	Fee Code	Fee (\$)	Fee Description	Fee Paid
105	130	205	65	Surcharge - late filing fee or oath	
127	50	227	25	Surcharge - late provisional filing fee or cover sheet.	
139	130	139	130	Non-English specification	
147	2,520	147	2,520	For filing a request for ex parte reexamination	
112	920*	112	920*	Requesting publication of SIR prior to Examiner action	
113	1,840*	113	1,840*	Requesting publication of SIR after Examiner action	
115	110	215	55	Extension for reply within first month	
116	400	216	200	Extension for reply within second month	
117	920	217	460	Extension for reply within third month	
118	1,440	218	720	Extension for reply within fourth month	
128	1,960	228	980	Extension for reply within fifth month	
119	320	219	160	Notice of Appeal	
120	320	220	160	Filing a brief in support of an appeal	
121	280	221	140	Request for oral hearing	
138	1,510	138	1,510	Petition to institute a public use proceeding	
140	110	240	55	Petition to revive - unavoidable	
141	1,280	241	640	Petition to revive - unintentional	
142	1,280	242	640	Utility issue fee (or reissue)	
143	460	243	230	Design issue fee	
144	620	244	310	Plant issue fee	
122	130	122	130	Petitions to the Commissioner	
123	50	123	50	Processing fee under 37 CFR 1.17(q)	
126	180	126	180	Submission of Information Disclosure Stmt	
581	40	581	40	Recording each patent assignment per property (times number of properties)	
146	740	246	370	Filing a submission after final rejection (37 CFR 1.129(a))	
149	740	249	370	For each additional invention to be examined (37CFR 1.129(b))	
179	740	279	370	Request for Continued Examination (RCE)	
169	900	169	900	Request for expedited examination of a design application	

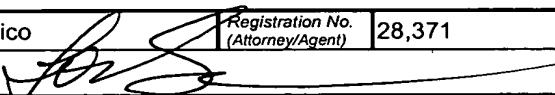
Other fee (specify)

\*Reduced by Basic Filing Fee Paid

**SUBTOTAL (3) (\$ 0.00)**

\*\*or number previously paid, if greater; For Reissues, see above

**SUBMITTED BY****Complete (if applicable)**

Name (Print/Type)	Thomas J. D'Amico	Registration No. (Attorney/Agent)	28,371	Telephone	(202) 828-2232
Signature				Date	September 26, 2002

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5/B  
September  
10-9-02

Docket No.: M4065.0159/P159-A  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Li Li, et al.

Application No.: 09/902,691

Group Art Unit: 2815

Filed: July 12, 2001

Examiner: P. Brock

For: METHOD OF CONTROLLING  
STRIATIONS AND CD LOSS IN  
CONTACT OXIDE ETCH

AMENDMENT

**Box Non-Fee Amendment**  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated June 26, 2002 (Paper No. 4), please amend the above-identified U.S. Patent application as follows:

In the Claims:

Please rewrite claim 59 as shown in the Replacement Claims.

Please add the following new claims:

- ~~92. (New) An integrated circuit substrate formed by a method comprising the steps of:~~
- ~~09/27/2002 NGUYEN 00000022 09902691~~
- ~~01 FC:103~~
- ~~B1 cont~~
92. (New) An integrated circuit substrate formed by a method comprising the steps of:  
(a) placing said integrated circuit substrate into a reactive chamber;  
(b) introducing an etching gas into said chamber;  
(c) generating a plasma of said etching gas at a first power level and contacting said substrate with said first power level plasma for a first predetermined time; and

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